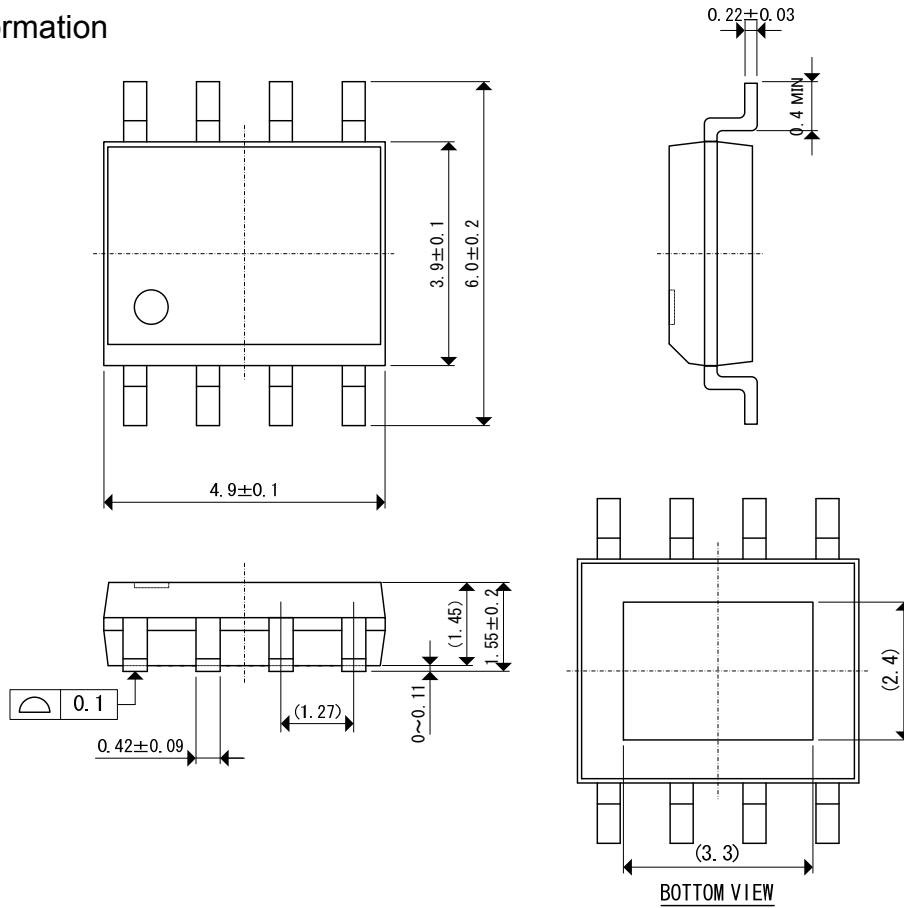


Packaging Information / Reference Pattern Layout Dimensions

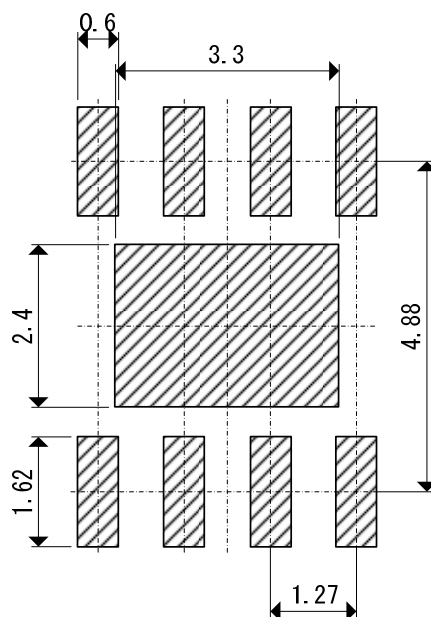
● SOP-8FD

Unit: mm

■ Packaging Information

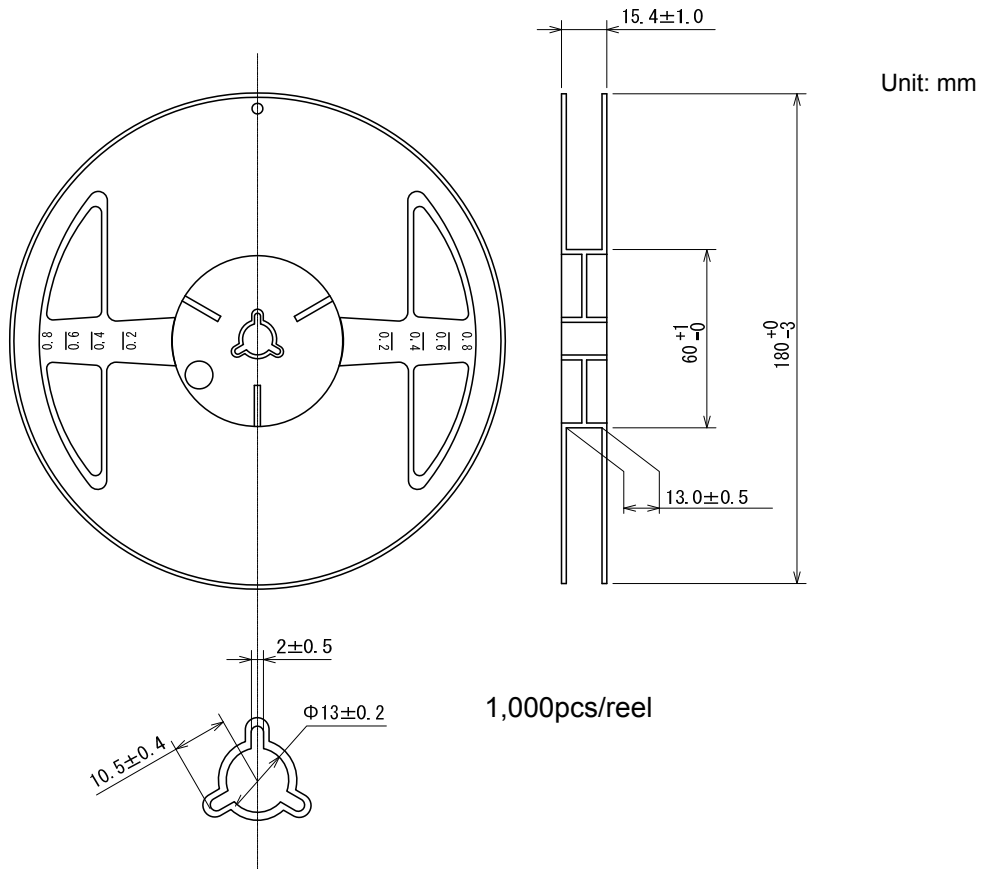


■ Reference Pattern Layout Dimension

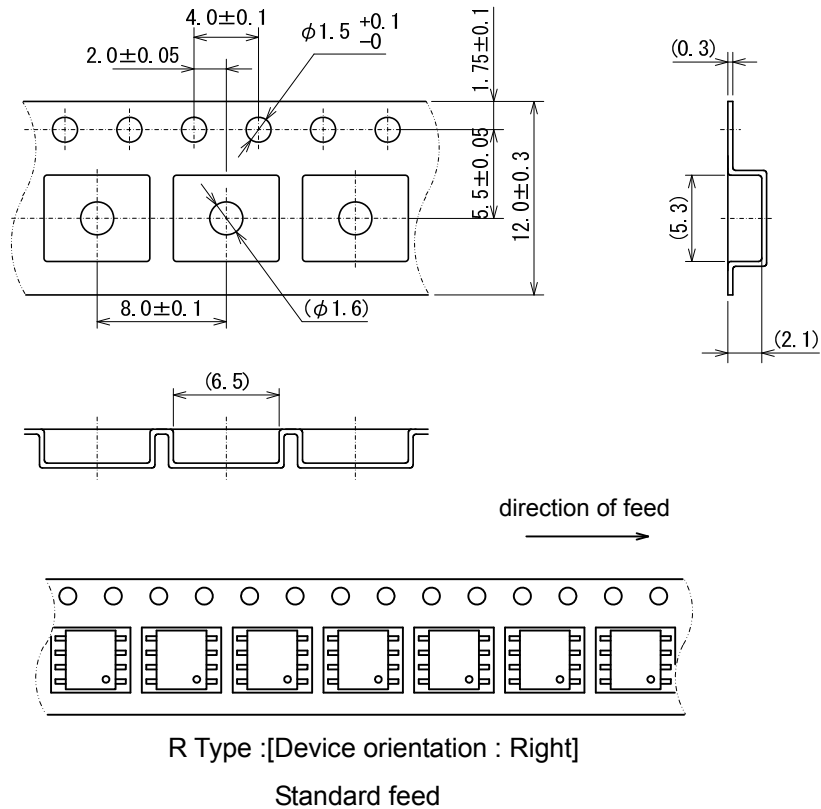


Taping Specifications

●SOP-8FD Reel



●Taping Specifications

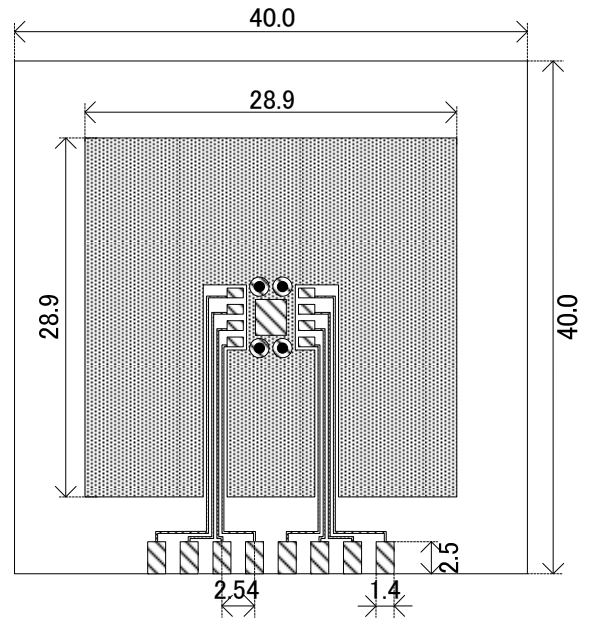


● SOP-8FD Power Dissipation

Power dissipation data for the SOP-8FD is shown in this page. The value of power dissipation varies with the mount board conditions. Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

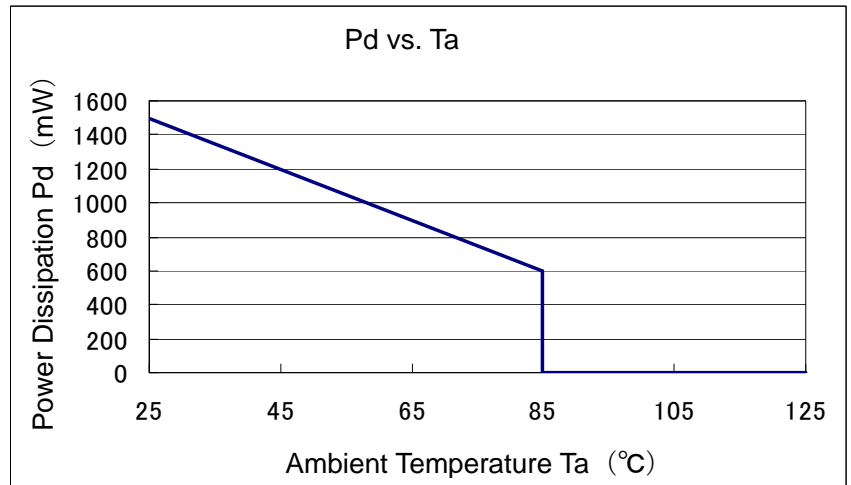
- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter



2. Power Dissipation vs. Ambient temperature (85°C)

Board Mount (T_j max = 125°C)

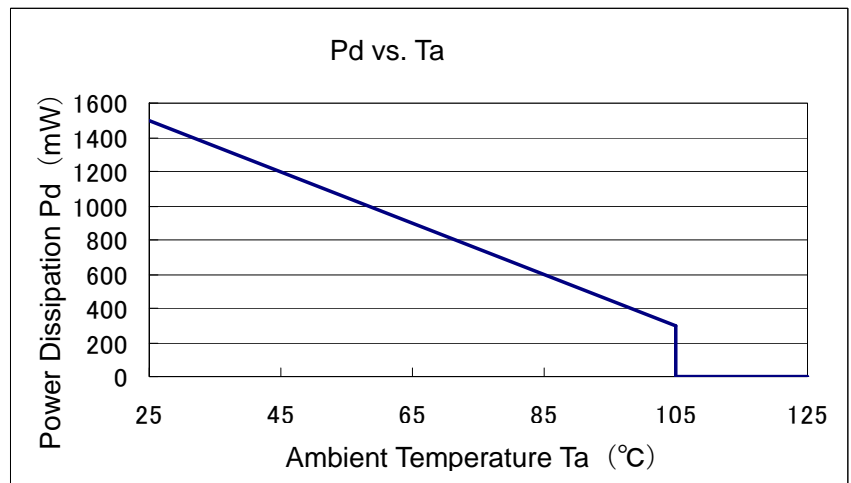
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
85	600	



3. Power Dissipation vs. Ambient temperature (105°C)

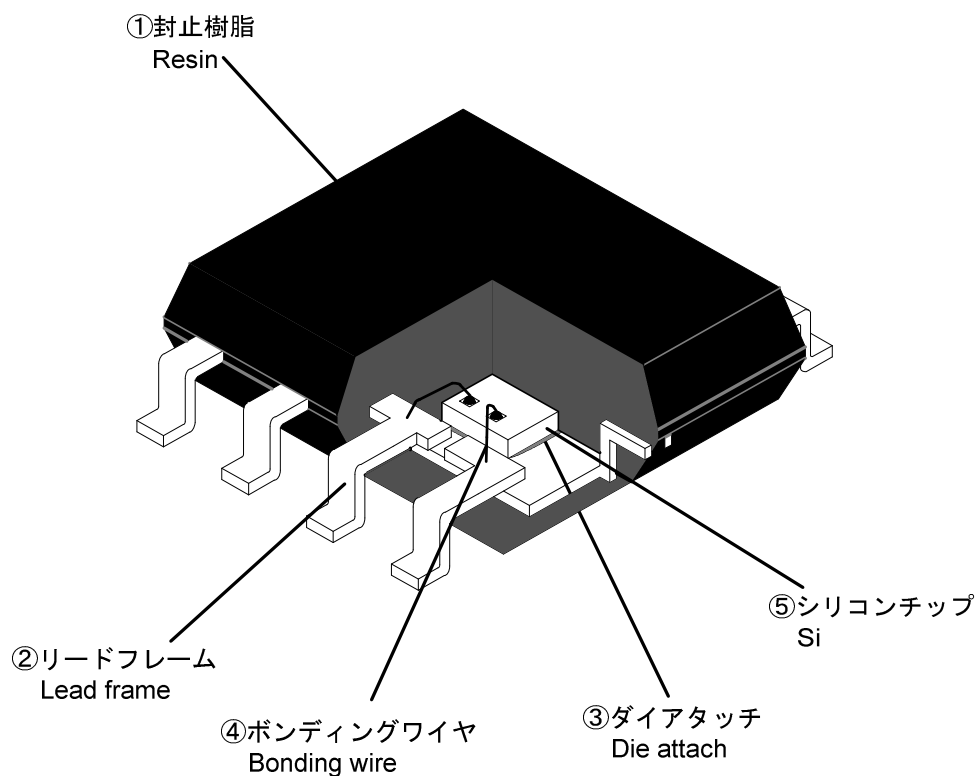
Board Mount (T_j max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
105	300	



SOP-8FD構造図 SOP-8FD Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Si	Si	

捺印表示 Marking	レーザー Laser marking
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